

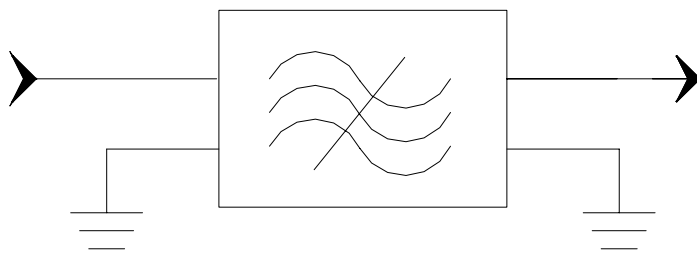
Specifications

Parameter	Unit	Minimum	Typical	Maximum
Center Frequency	MHz	139.875	140	140.125
Insertion Loss	dB	-	28.9	31
1.5 dB Bandwidth	MHz	24.1	24.24	-
24 dB Bandwidth	MHz	-	25.1	25.2
Passband Variation	dB	-	0.8	1.5
Ultimate Rejection	dB	40	45	-
Absolute Delay	usec	-	2.4	2.5
Material Temperature coefficient	KHz/°C	-11.48		
Ambient Temperature	°C	25		
Package Size	DIP3512 (35.0x12.8x4.7mm ³)			

Notes:


1. All specifications are based on the test circuit shown
2. In production, devices will be tested at room temperature to a guardbanded specification to ensure electrical compliance over temperature
3. Electrical margin has been built into the design to account for the variations due to temperature drift and manufacturing tolerances
4. This is the optimum impedance in order to achieve the performance show

Matching Configuration



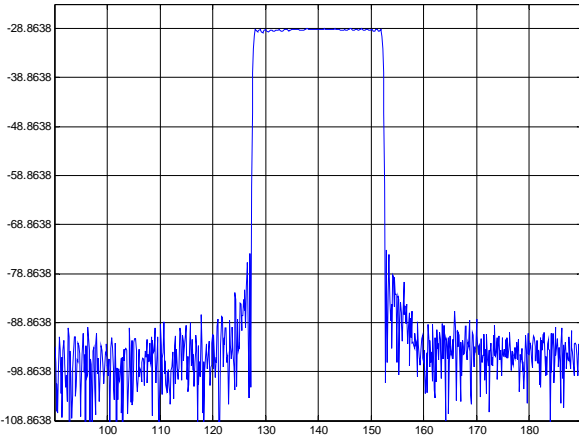
Source/Load Impedance=50 ohm

Notes - Component values may change depending on board layout.

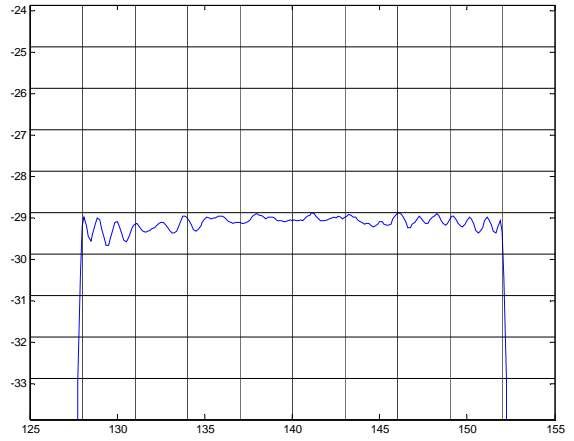
	SIPAT Co., Ltd. (CETC No. 26 Research Institute) Nanping Huayuan Road No. 14 Chongqing, China, 400060	Part Number	LBN14073	
		Rev. Date	2005-11-29	
		Rev.	2.0	Page 1/3

Typical Performance

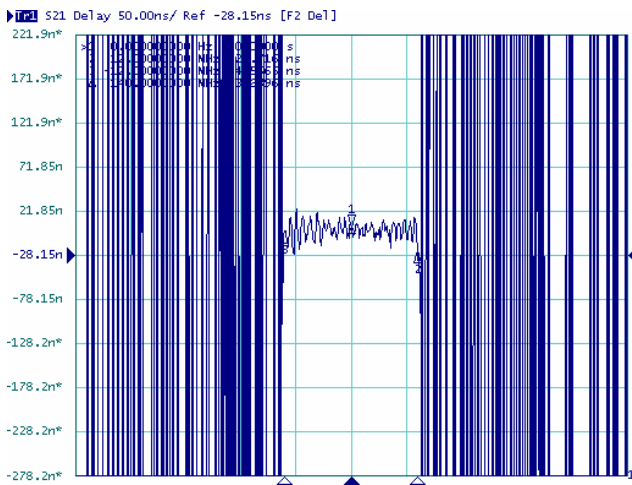
Frequency Respond



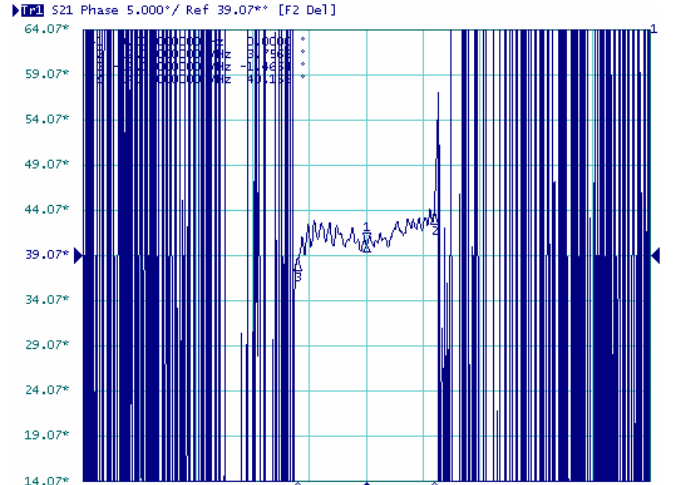
Passband Respond



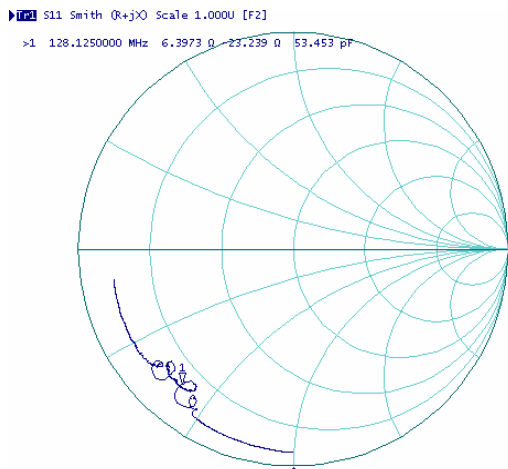
Group delay Variation ($F_0 \pm 12\text{MHz}$)



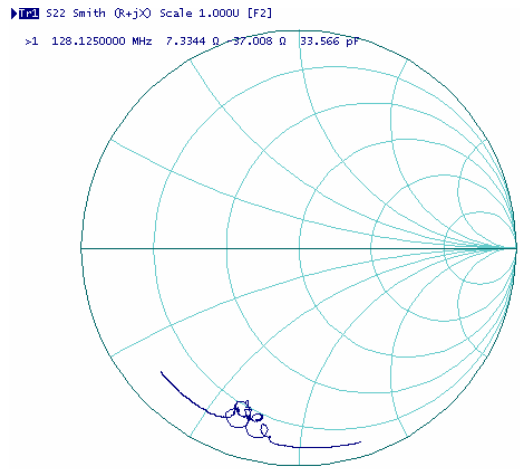
Phase Linearity ($F_0 \pm 12\text{MHz}$)



Smith Chart S11



Smith Chart S22



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